Honeywell

High-Performance Process Manager Planning

HP02-500

TotalPlant

Section 2 – HPM Description

2.1 Overview

Section contents

The topics covered in this section are:

HPM major assemblies

The High-Performance Process Manager subsystem (HPM) consists of major assemblies described in the following subsections. The major High-Performance Process Manager assemblies are

- High-Performance Process Manager Module (HPMM) card file
- Input/Output Processor (IOP) card file
- Input/Output Processor (IOP) card
- I/O Link Extender
- Field Termination Assembly (FTA)
- Power System

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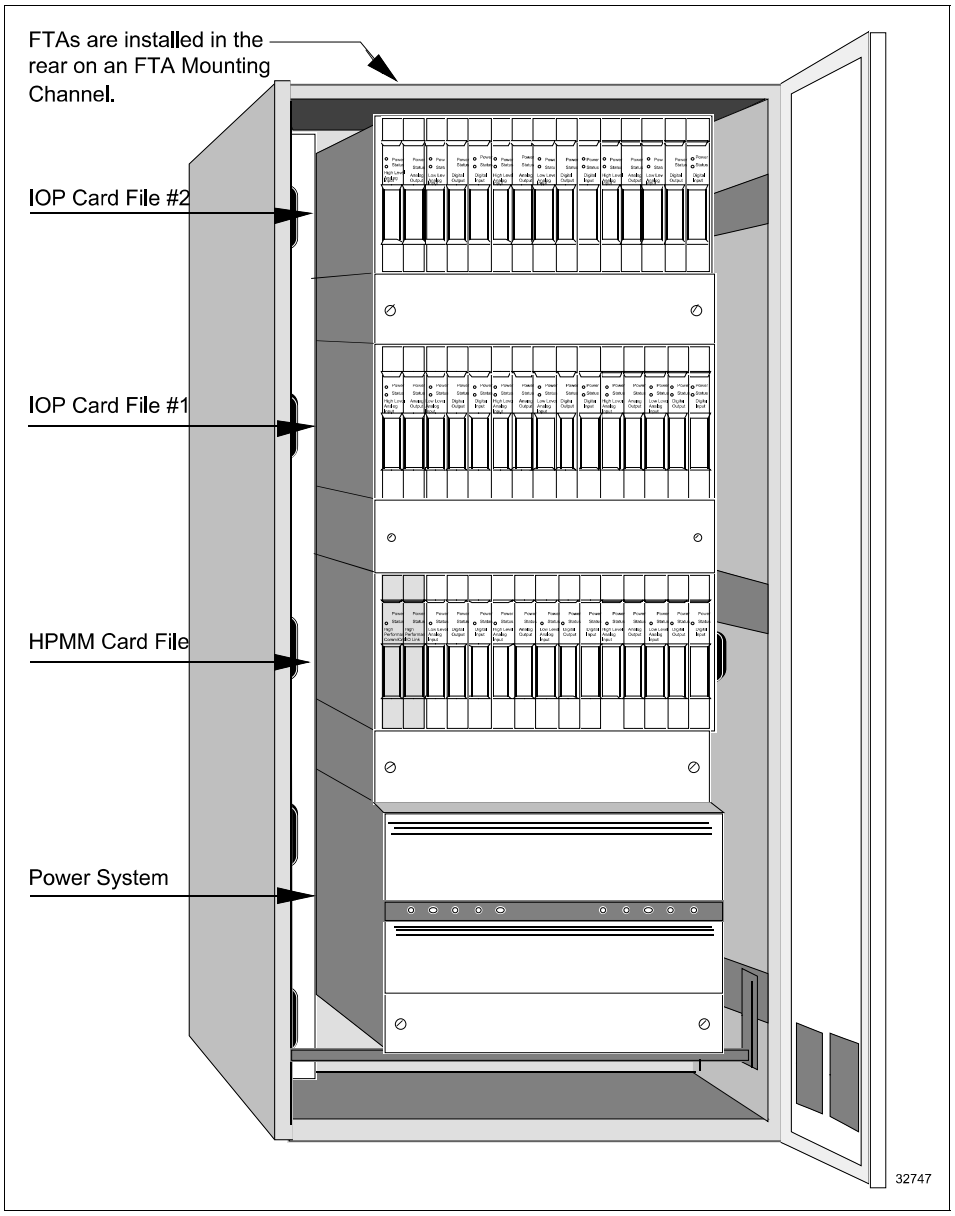
Nonredundant HPM cabinet layout

Figure 2-1 is an illustration of a single High-Performance Process Manager cabinet containing a nonredundant High-Performance Process Manager Module (HPMM) with supporting assemblies. The HPMM cards (2) and the IOPs cards are installed in 15-Slot HPMM card files. IOP cards occupy the IOP card files.

Figure 2-1 Nonredundant HPMM Cabinet Layout



2.2 Card Files

Introduction

There are nine card file models. Three models are not CE Compliant and six models are CE Compliant. Table 2-1 lists the nine card file models. All models are also available with conformal coating (a model number with a prefix of MC, rather than MU).

Table 2-1 Card File Models

Card File Description	CE Compliant	Non-CE Compliant
Left 7-Slot HPMM or IOP	N/A	MU-HPFH01
Right 7-Slot HPMM or IOP	N/A	MU-HPFH11
15-Slot HPMM or IOP	N/A	MU-HPFX02
Left 7-Slot HPMM	MU-HPFH03	N/A
Right 7-Slot HPMM	MU-HPFH13	N/A
15-Slot HPMM	MU-HPFX03	N/A
Left 7-Slot IOP	MU-HPFI03	N/A
Right 7-Slot IOP	MU-HPFI13	N/A
15-Slot IOP	MU-HPFI23	N/A

Non-CE Compliant card file models

The non-CE Compliant card file models can be designated as an HPMM card file or an IOP card file by either installing an HPMM card set in the two left-most card slots or installing IOP cards.

CE Compliant card file models

Unlike the non-CE Compliant card file models, the CE Compliant card file models are designated either an HPMM card file or an IOP card file because even though their is no electrical difference in the backpanel, they differ mechanically. The addition of a ground plate and filtered IOP connectors in the two left-most slots prohibits the installation of an HPMM card set.

The card file is designated an IOP card file when the ground plate and filtered connectors are present.

The card file is designated an HPMM card file when the ground plate and filtered connectors are absent.

Conversion kit

A CE Compliant HPMM card file can be converted to an IOP card file with a model MU-ZPFI03 upgrade kit. The kit adds 2 filtered IOP adapter connectors to the two left-most card slots and a ground plate extension.

2.2.1 HPMM Card Files

Three types of HPM card files

There are three types of HPMM card files. The two left-most slots of each type are populated by the three assemblies that comprise the HPMM. The remaining slots accommodate IOPs.

If the card file is a non-CE Compliant card file, the two left-most slots of each type can also accommodate IOPs with no alterations. The card file is then designated an IOP card file.

HPMM description

The High-Performance Process Manager Module (HPMM) is composed of two card assemblies that install in the two left-most slots in a 7-Slot or 15-Slot card file, and a UCN interface module that mounts and connects to the 50-pin connector that is directly below the left-most card.

The three HPMM assemblies are identified as follows:

- High-Performance Communications/Control (High-Performance Comm/Control) card
- High-Performance I/O Link Interface (High-Performance I/O Link) card
- High-Performance UCN Interface (HPM UCN Interface) module

The HPM UCN Interface module connects to the 50-pin connector below the High-Performance Comm/Control card.

Left 7-Slot HPMM card file description

The Left 7-Slot card file accepts the two HPMM cards and the HPM UCN Interface module that comprise the HPMM, and accommodates up to five IOP cards. The card slots are numbered 1 through 7, starting at the left-most position.

The High-Performance Comm/Control and High-Performance I/O Link cards occupy slots 1 and 2, while the HPM UCN Interface module mounts below slot 1 and connects to its 50-pin connector.

Slots 3 through 7 can accommodate IOP cards. The IOP card slots assume numerical I/O Link Interface addresses of 3 through 7 and binary I/O Link Interface addresses of 2 through 6.

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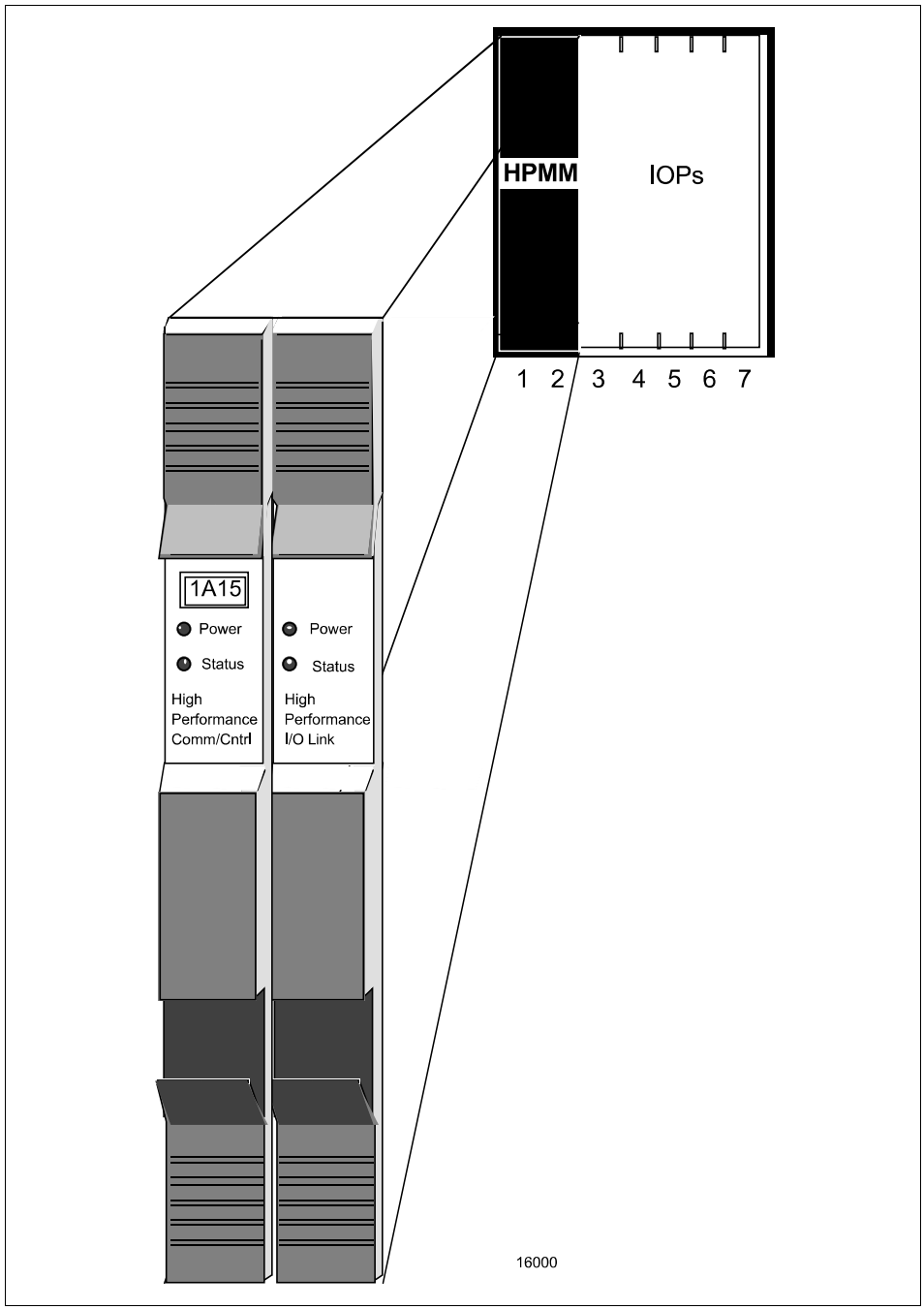
2.2.1 HPMM Card Files, Continued

Left 7-Slot HPMM card file illustration

Figure 2-2 is an illustration of a Left 7-Slot HPMM card file and the two HPMM cards that occupy slots 1 and 2.

Figure 2-2 Left 7-Slot HPMM Card File



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2.2.1 HPMM Card Files, Continued

Right 7-Slot HPMM card file description

The description of the Right 7-Slot HPMM card file is identical to the Left 7-Slot HPMM card file, except the two HPMM cards and the UCN interface module occupy slots 9 and 10. The card slots are numbered 9 through 15.

Slots 11 through 15 accommodate IOP cards. The IOP card slots assume numerical I/O Link Interface addresses of 11 through 15 and binary I/O Link Interface addresses of 10 through 14.

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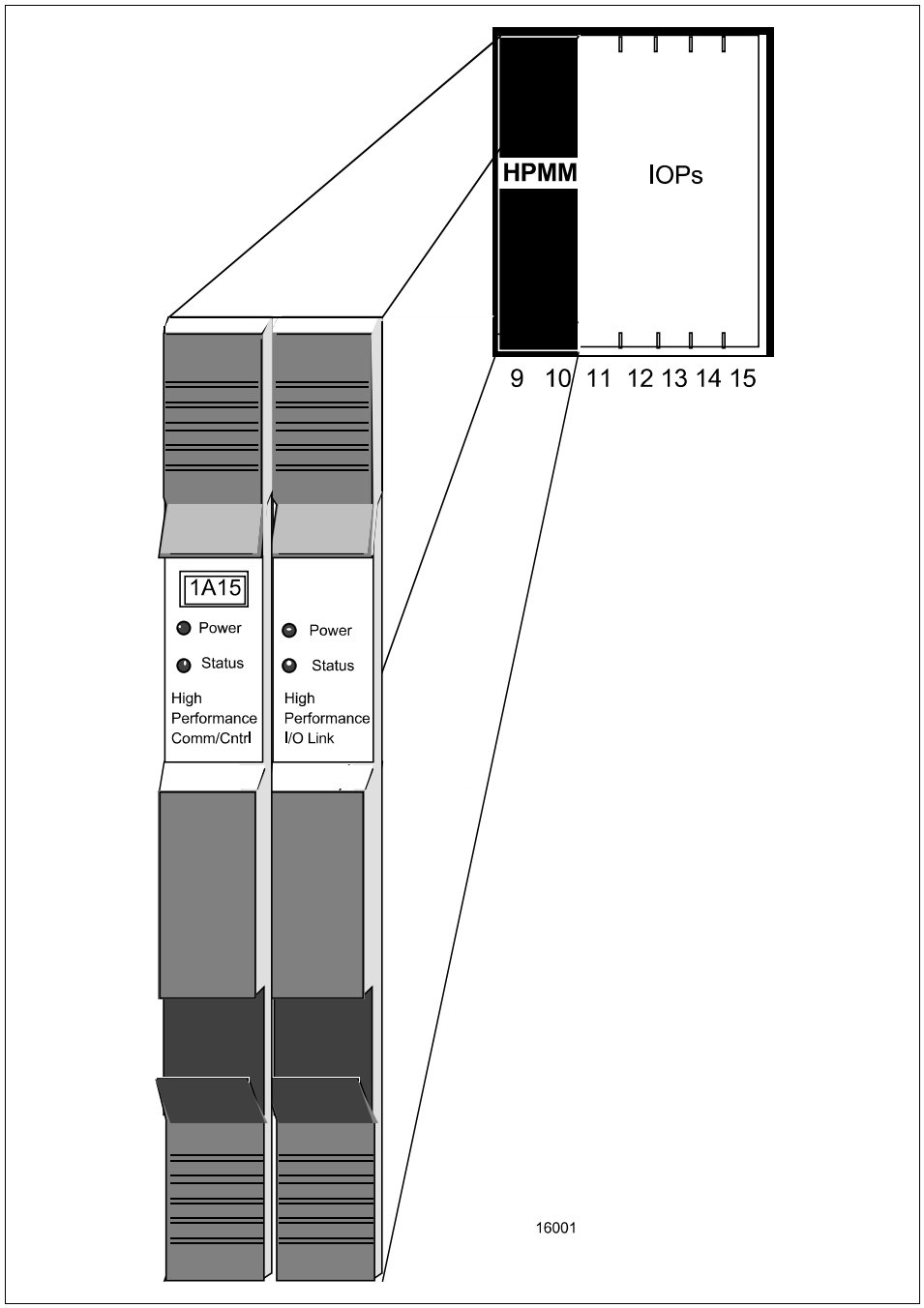
2.2.1 HPMM Card Files, Continued

Right 7-Slot HPMM card file illustration

Figure 2-3 is an illustration of a Right 7-Slot HPMM card file and the two HPMM cards that occupy slots 9 and 10.

Figure 2-3 Right 7-Slot HPMM Card File



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2.2.1 HPMM Card Files, Continued

15-Slot HPMM card file description

The 15-Slot card file accepts the two HPMM cards and the UCN interface module that comprise the HPMM, and accommodates up to thirteen IOP cards. The card slots are numbered 1 through 15, starting at the left-most position.

The High-Performance Comm/Control and High-Performance I/O Link cards occupy slots 1 and 2, while the HPM UCN Interface module mounts below slot 1 in its 50-pin connector.

Slots 3 through 15 can accommodate IOP cards. The IOP card slots assume numerical I/O Link Interface addresses of 3 through 15 and binary I/O Link Interface addresses of 2 through 14.

When populated with the HPMM cards, the card file is designated a 15-Slot HPMM card file.

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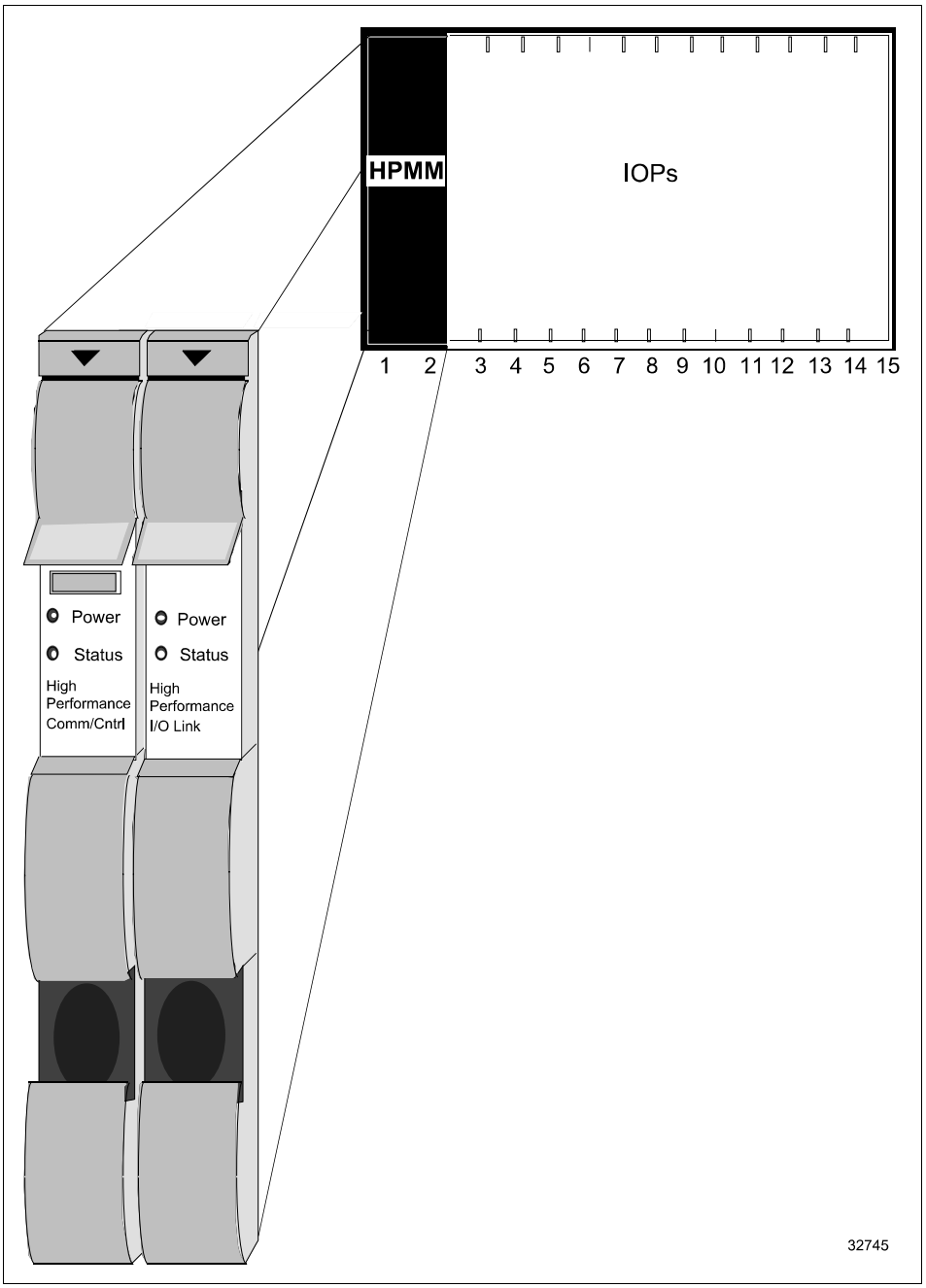
2.2.1 HPMM Card Files, Continued

15-Slot HPMM card file illustration

Figure 2-4 is an illustration of a 15-Slot HPMM card file and the two HPMM cards that occupy slots 1 and 2.

Figure 2-4 15-Slot HPMM Card File



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2.2.1 HPMM Card Files, Continued

7-Slot HPMM card file usage

The two types of 7-Slot HPMM card files are intended to be used in a small HPM subsystem.

When the subsystem consists of nonredundant HPMMs, a Left 7-Slot HPMM card file must be installed. For a subsystem that requires redundant HPMMs, Left and Right 7-Slot HPMM card files are installed. Both card files are assigned the same the same I/O Link Interface address. There is no slot 8 because the card file slots are numbered 1 through 7 and 9 through 15.

15-Slot HPMM card file usage

The 15-Slot HPMM card file is intended for use in a larger HPM subsystem, either with nonredundant or redundant HPMMs. Unlike the 7-Slot HPMM card file, there is no “loss” of a card slot.

HPMM functionality

The HPMM provides the following functions:

- Communications with the Local Control Network (LCN) Network Interface Module (NIM) through the Universal Control Network (UCN)
- A Communications processor (Motorola 68LC040)
- Communications through the I/O Link Interface with Input/Output Processors (IOPs) and I/O Link Extenders
- A Control processor (Motorola 68040)
- Separate and shared memory for the Communications and Control processors
- An I/O Link processor (Intel 80C32) with SRAM
- HPMM redundancy control

2.2.2 Input/Output Processor (IOP) Card Files

IOP card file descriptions

The 7-Slot and 15-Slot IOP card files are electrically identical to the HPMM card files, except that an HPMM card set is not installed in the card file. IOPs can be installed in the two left-most card slots.

Non-CE Compliant card files

Non-CE Compliant HPMM and IOP card files differ only in the application. Electrically and mechanically, their backpanels are the same. The card file model numbers are the same.

CE Compliant card files

CE Compliant HPMM and IOP card files differ mechanically. IOP card files have filtered IOP connectors and connector ground plates. Electrically, their backpanels are the same. The card file model numbers are different.

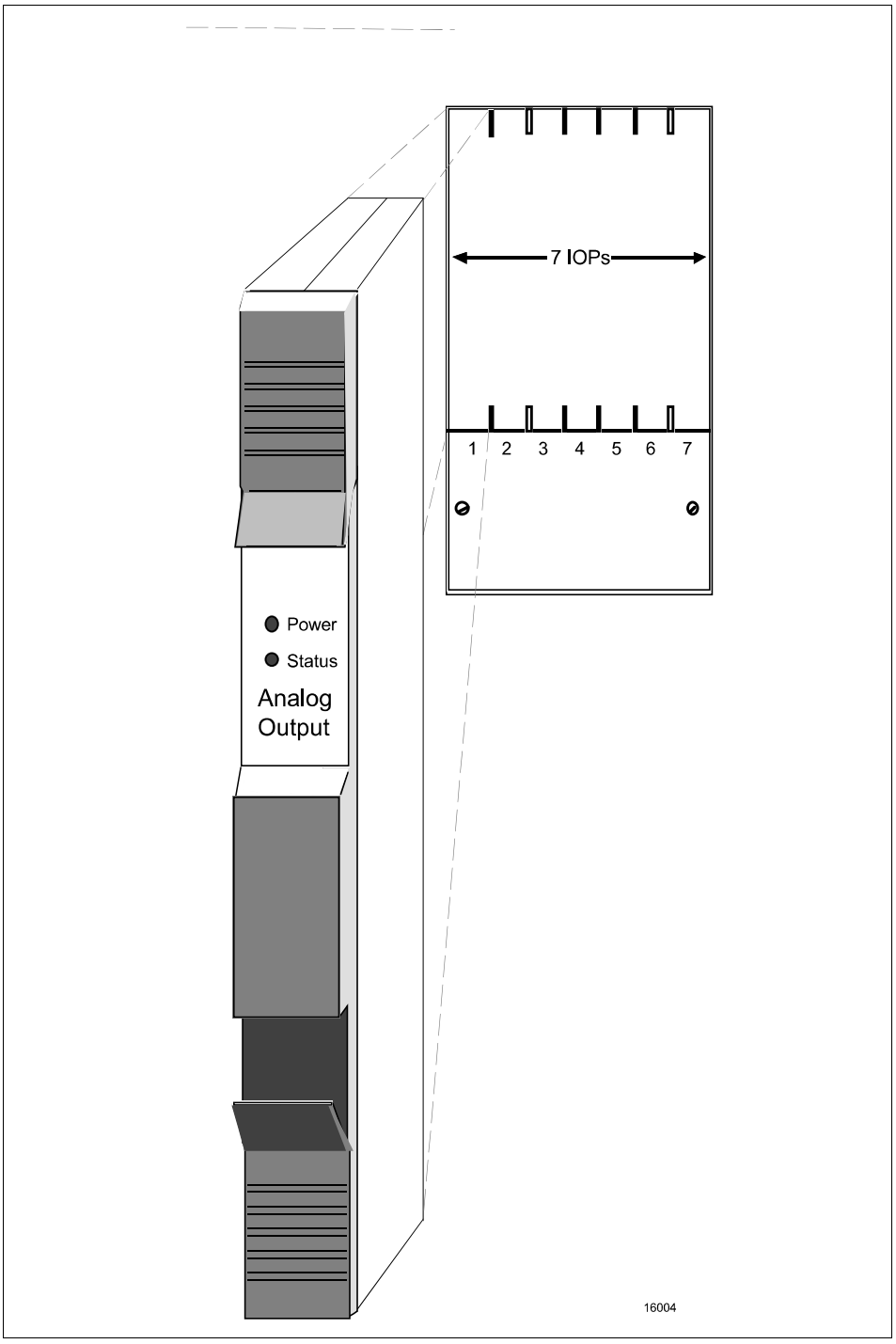
Continued on next page

2.2.2 Input/Output Processor (IOP) Card Files, Continued

Left 7-Slot IOP card file

Figure 2-5 illustrates a Left 7-Slot IOP card file.

Figure 2-5 Left 7-Slot IOP Card File



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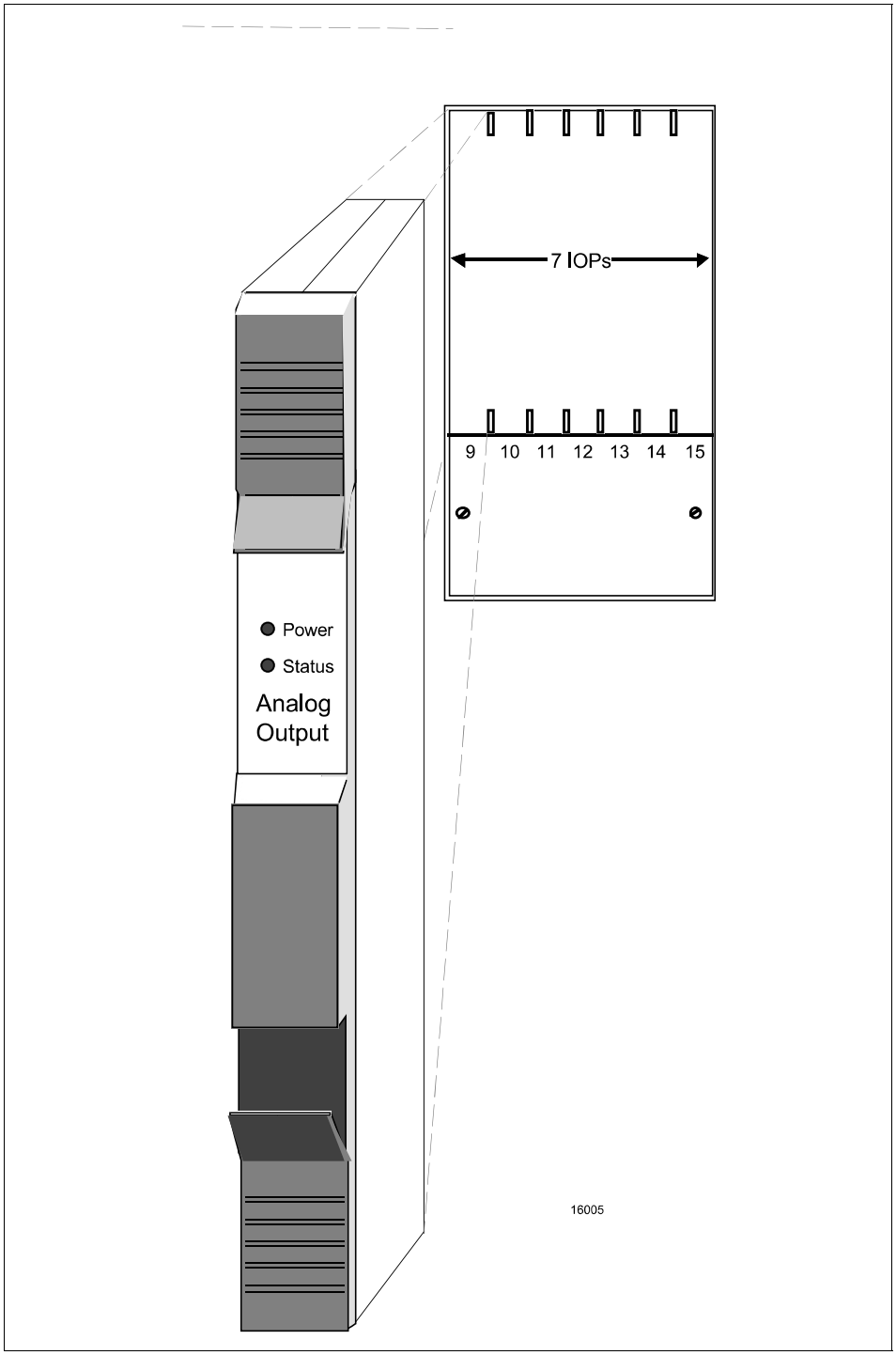
2.2.2 Input/Output Processor (IOP) Card Files, Continued

Right 7-Slot IOP card file

Figure 2-6 illustrates a Left 7-Slot IOP card file.

Figure 2-6 Right 7-Slot IOP Card File



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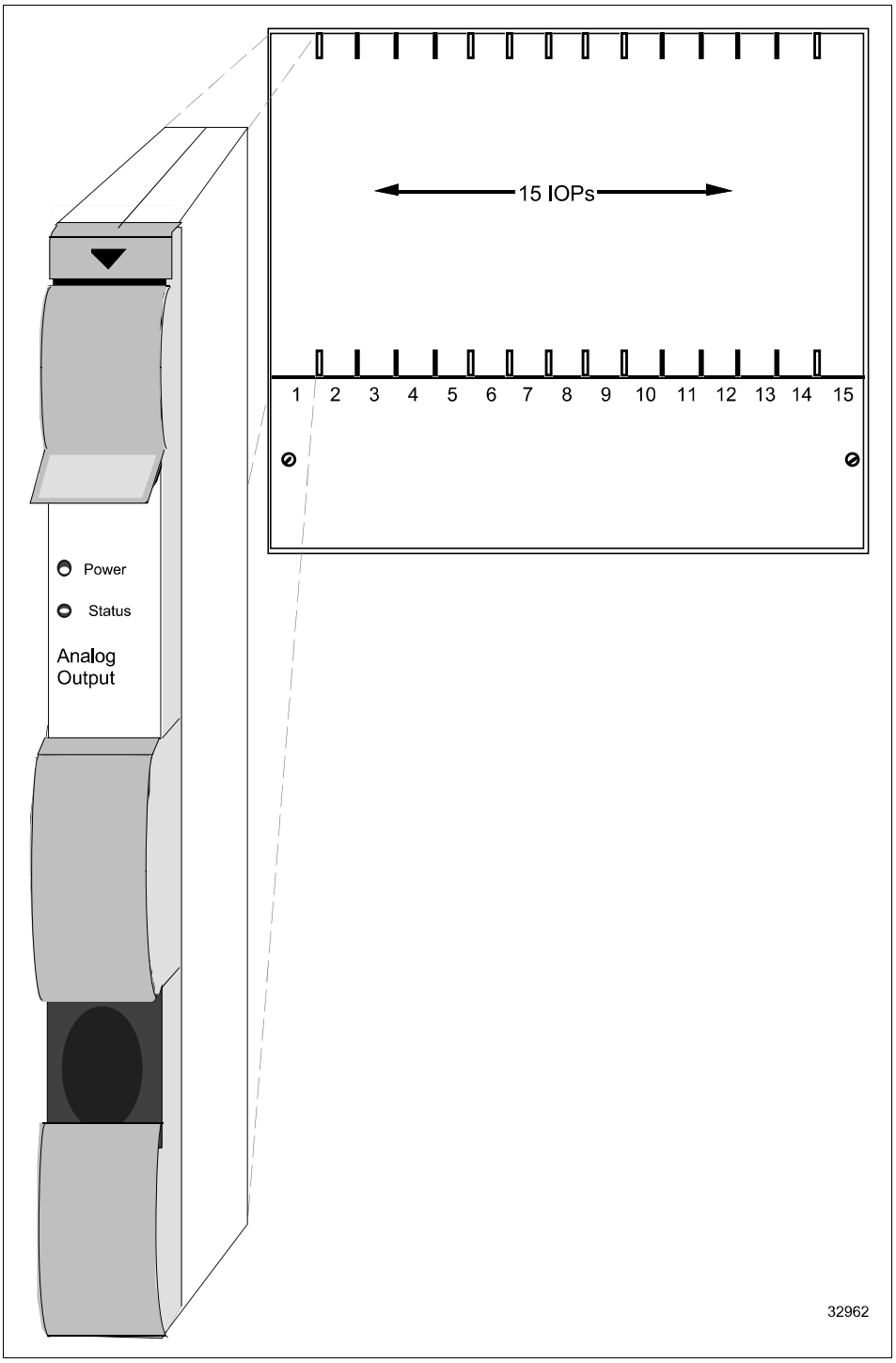
2.2.2 Input/Output Processor (IOP) Card Files, Continued

15-Slot IOP card file

Figure 2-7 illustrates a 15-Slot IOP card file.

Figure 2-7 15-Slot IOP Card File



2.3 Input/Output Processor (IOP) Cards

Types of Input/Output Processors (IOPs)

There are thirteen types of Input/Output Processor (IOP) card assemblies. Some IOP card types interface with more than one type of Field Termination Assembly (FTA). The functional types of IOPs are

- High Level Analog Input (HLAI)
- Low Level Analog Input (LLAI)
- Low Level Analog Multiplexer (LLMux)
- Remote Hardened Low Level Analog Multiplexer (RHMUX)
- Digital Input (DI)
- Analog Output (AO)
- Digital Output (DO)
- Smart Transmitter Interface (STI)
- Smart Transmitter Interface Multivariable (STIM)
- Pulse Input (PI)
- Digital Input Sequence of Events (DISOE)
- Serial Device Interface (SDI)
- Serial Interface (SI)

Card file configurations

Additional IOP card file slots can be added to any High-Performance Process Manager subsystem. Each IOP card file accommodates up to 7 or 15 IOPs as illustrated in Figures 2-5 through 2-7. A total of eight 15-Slot card files or 7-Slot card file pairs (Left and Right), including HPMM card files, can exist in a High-Performance Process Manager subsystem. However, the limit is eight because each 15-Slot card file and pair of 7-Slot card files must be assigned an I/O Link Interface address between 0 and 7.

IOP card files can be installed at remote locations with the use of fiber optic I/O Link Extenders, as well as locally in the cabinet or cabinet complex containing the HPMM card file(s).

A total of 40 primary IOPs, 40 secondary (redundant) IOPs, and 3 I/O Link Extenders (a maximum of 8 I/O Link Extender cards) can exist in a single High-Performance Process Manager subsystem.

2.3.1 IOP Redundancy

IOP redundancy

The HPM subsystem supports IOP redundancy for the following types of IOPs:

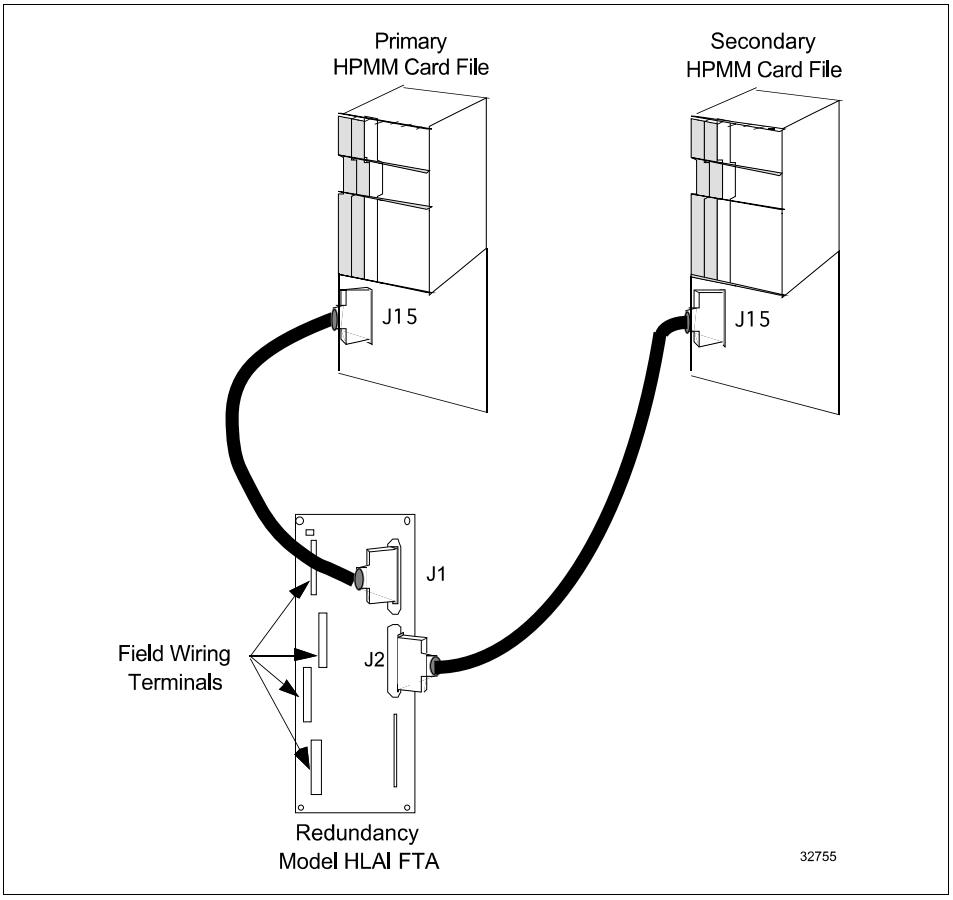
- High Level Analog Input (HLAI)
- Smart Transmitter Interface (STI or STIM)
- Analog Output (AO)
- Digital Input (DI)
- Digital Input Sequence of Events (DISOE)
- Digital Output (DO)

Presently, not all Digital Input and Digital Output IOP models support redundancy.

Redundant HLAI IOPs

A pair of IOPs can be connected in a redundant configuration with both IOPs connected by separate cables to the same FTA. Figure 2-8 illustrates an HLAI FTA that interfaces with a pair of HLAI IOPs that are installed in separate card files.

Figure 2-8 HLAI FTA with Redundant HLAI IOPs



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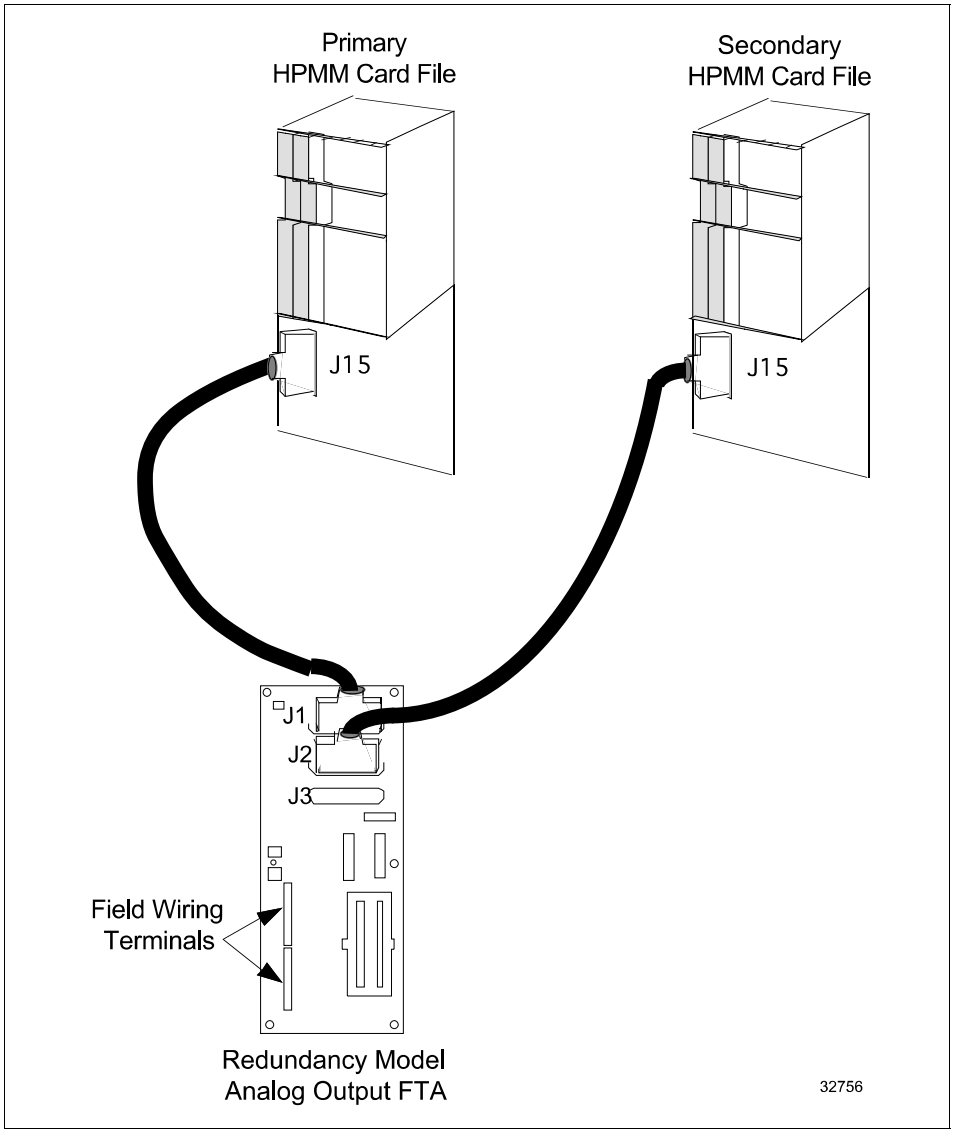
Redundant AO IOPs

Output type FTAs can also interface with two IOPs with separate cables, and an automatic selector switch on the FTA selects which IOP's output drives the field wiring terminal connectors on the FTA. Figure 2-9 is an illustration of an Analog Output (AO) FTA interface with two Analog Output IOPs.

Figure 2-9 Analog Output FTA with Redundant Analog Output IOPs



2.4 I/O Link Extender (Fiber Optic Link)

Introduction

The I/O Link Extender provides the ability to locate 7-Slot or 15-Slot IOP card files and associated FTAs up to 8 kilometers (5 miles) from the HPMM(s). Two types of I/O Link Extenders and their associated fiber optic couplers are available, the "Standard" I/O Link Extender that provides up to a 1.3 kilometer (4000 feet) link, and the "Long Distance" I/O Link Extender which provides up to an 8 kilometers (5 miles) link. The connection is made using a pair of fiber optic transmission cables, driven and terminated by a fiber optic coupler that mates with the connector located directly below the card file slot in which the I/O Link Extender card is installed.

Features

An I/O Link Extender consists of two pairs I/O Link Extender cards, one for Link A and one for Link B, and associated fiber optic couplers at each end of the fiber optic link. The I/O Link Extender cards and their fiber optic couplers occupy two slots in an HPMM or IOP card file.

Remote card files

Every remote card file, or complex of IOP card files, requires two I/O Link Extender cards and two fiber optic couplers, one for Link A and one for Link B.

Fiber optic cable length

The maximum fiber optic cable length is dependent upon the number of splices and quality of the cable (dB loss per meter of cable). This maximum can be between 0.98 and 1.3 kilometers for the Standard I/O Link Extender and 8 kilometers for the Long Distance I/O Link Extender.

I/O Link Extender planning

I/O Link Extender planning can be found in Section 11 in this manual.

Standard I/O Link Extender

Each Standard I/O Link Extender card has an associated fiber optic coupler that can drive up to three pair of fiber optic cables. Each cable pair is terminated by a fiber optic coupler that terminates one fiber optic pair.

The Standard I/O Link Extender card will drive and terminate Link A or Link B, depending upon the card file number and slot number number. If the card file number and slot number number are both odd or both even, the card will drive Link A. If the card file number and slot number number are not both odd or both even, the card will drive Link B.

Two Standard I/O Link Extender cards, connecting up to six remote card files, can be installed in a HPMM card file, but the maximum number of primary IOPs is still 40 (plus 40 redundant IOPs).

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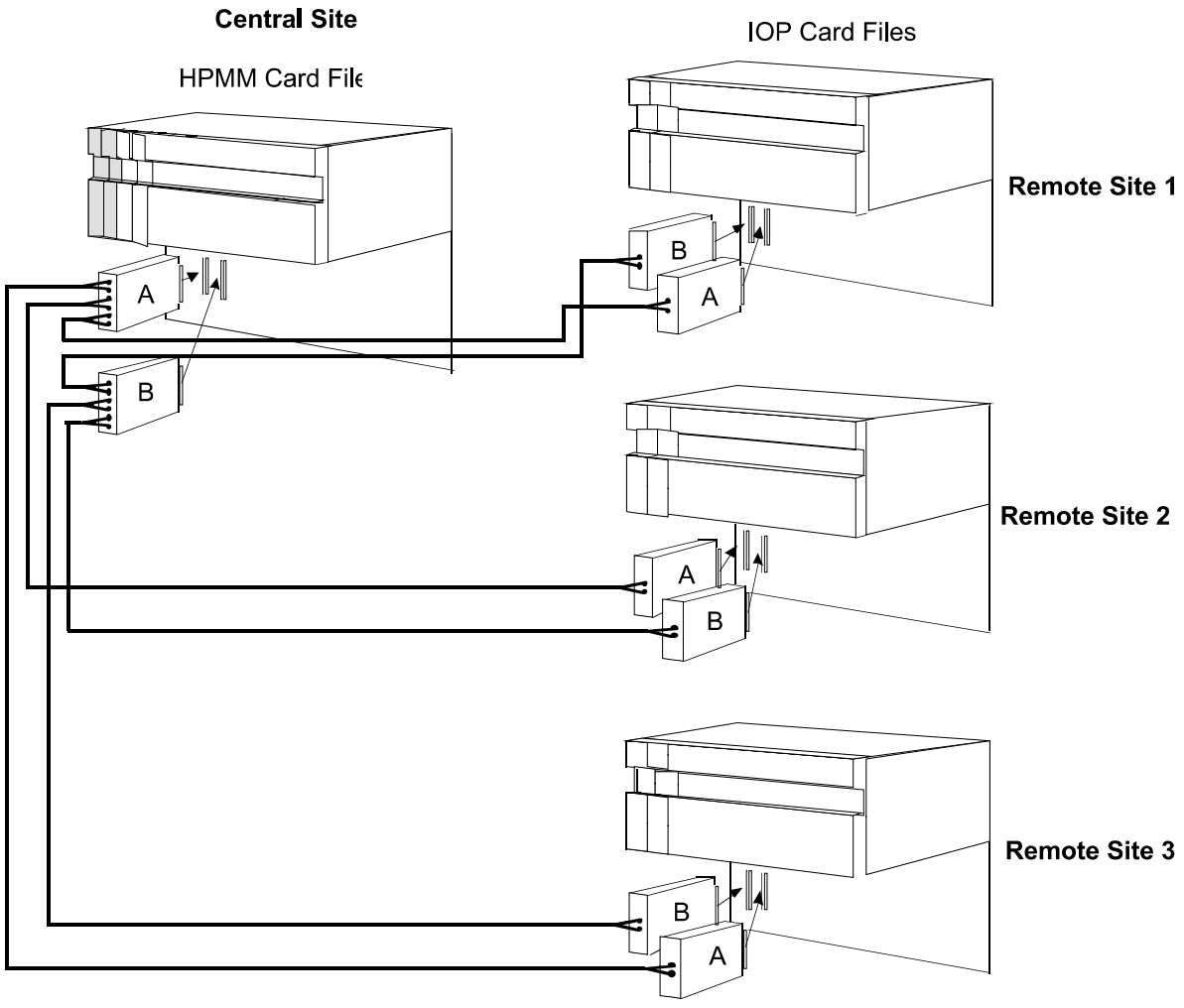
2.4 I/O Link Extender (Fiber Optic Link), Continued

Standard I/O Link Extender connections nonredundant HPMM

Figure 2-10 illustrates the interconnections for a Standard I/O Link Extender in a High-Performance Process Manager that contains a nonredundant HPMM.

Figure 2-10 Standard I/O Link Extender Interconnections with Nonredundant HPMM



NOTE

The following High-Performance Process Manager subsystem configuration is assumed.
1. The HPMM card file is configured as card file #1 (I/O Link address of 0).
2. Remote Site #1's IOP card file is configured as card file #2 (I/O Link address of 1).
3. Remote Site #2's IOP card file is configured as card file #3 (I/O Link address of 2).
4. Remote Site #3's IOP card file is configured as card file #4 (I/O Link address of 3).

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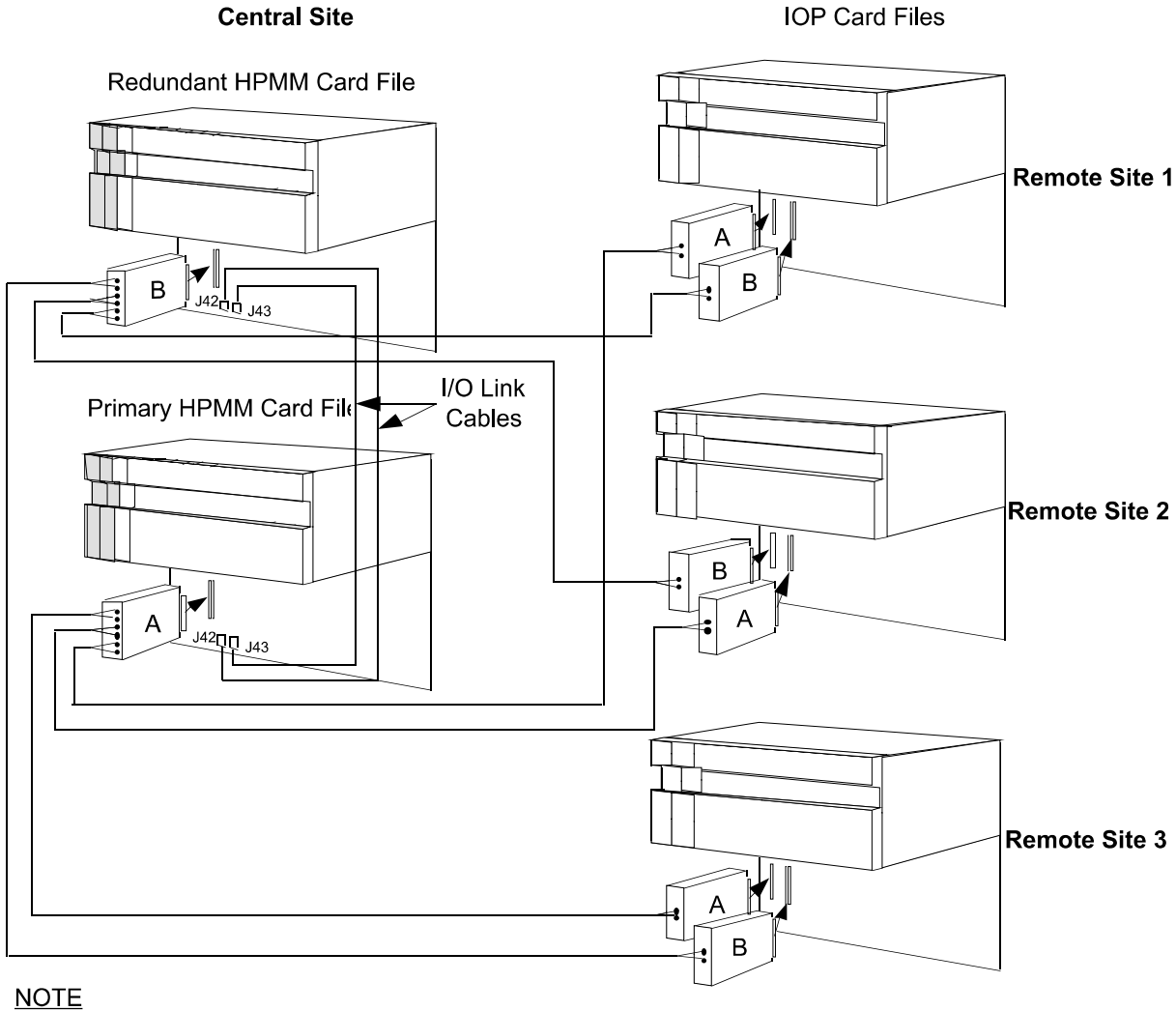
Standard I/O Link Extender connections redundant HPMMs

Figure 2-11 illustrates the interconnections for a Standard I/O Link Extender in a High-Performance Process Manager that contains redundant HPMMs.

Figure 2-11 Standard I/O Link Extender Interconnections with Redundant HPMMs



NOTE

The following High-Performance Process Manager subsystem configuration is assumed.

1. The lower HPMM card file is configured as card file #1 (I/O Link Address of 0).
2. The upper HPMM card file is configured as card file #2 (I/O Link Address of 1).
3. Remote Site #1's IOP card file is configured as card file #3 (I/O Link Address of 2).
4. Remote Site #2's IOP card file is configured as card file #4 (I/O Link Address of 3).
5. Remote Site #3's IOP card file is configured as card file #5 (I/O Link Address of 4).

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Long Distance I/O Link Extender

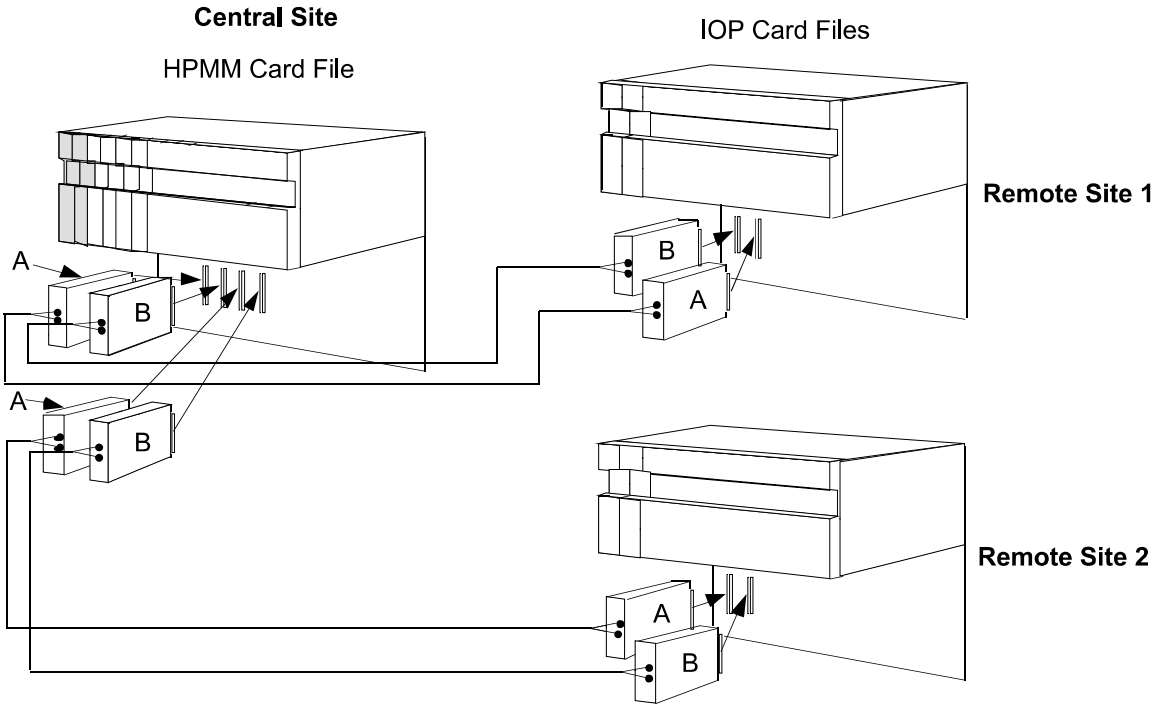
Each Long Distance I/O Link Extender card has an associated fiber optic coupler that drives a single pair of fiber optic cables. Each cable pair is terminated by a fiber optic coupler that terminates one fiber optic pair.

The Link A or Link B selection for the Long Distance I/O Link Extender is determined by a jumper on the card.

Long Distance I/O Link Extender connections nonredundant HPMM

Figure 2-12 illustrates the interconnections for a Long Distance I/O Link Extender in a High-Performance Process Manager that has a nonredundant HPMM.

Figure 2-12 Long Distance I/O Link Extender Interconnections with Nonredundant HPMM



NOTE

The following High-Performance Process Manager subsystem is assumed.
1. The HPMM card file is configured as card file #1 (I/O Link Address of 0).
2. Remote Site #1's IOP card file is configured as card file #2 (I/O Link Address of 1).
3. Remote Site #2's IOP card file is configured as card file #3 (I/O Link Address of 2).

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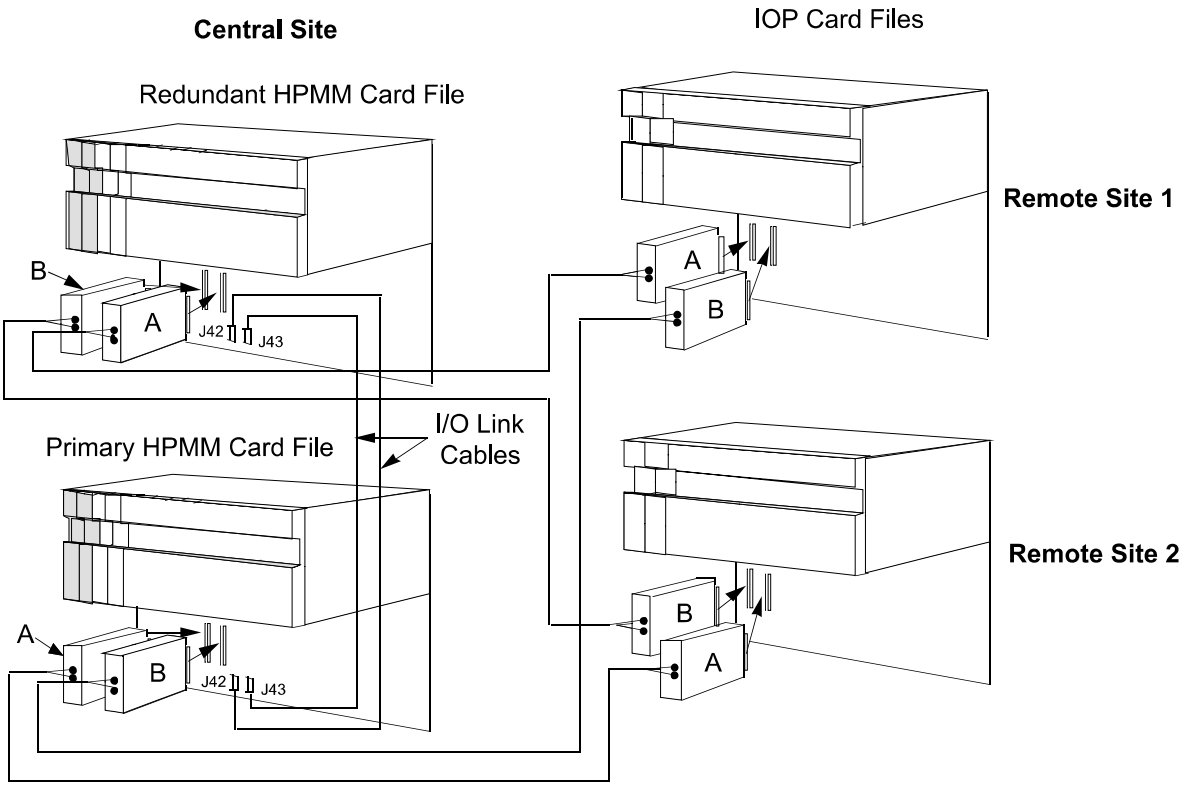
Long Distance I/O Link Extender connections redundant HPMMs

Figure 2-13 illustrates the interconnections for a Long Distance I/O Link Extender in a High-Performance Process Manager that has redundant HPMMs.

Figure 2-13 Long Distance I/O Link Extender Interconnections with Redundant HPMMs



NOTE

The following High-Performance Process Manager subsystem configuration is assumed.

1. The lower HPMM card file is configured as card file #1)I/O Link address of 0).
2. The upper HPMM card file is configured as card file #2 (I/O Link address of 1).
3. Remote Site #1's IOP card file is configured as card file #3 (I/O Link address of 2).
4. Remote Site #2's IOP card file is configured as card file #4 (I/O Link address of 3).

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2.5 Field Termination Assemblies (FTAs)

Description

Terminal connectors on the Field Termination Assembly (FTA) provide the connection points for the process control wiring. Fuses, relays, and resistors protect the FTA circuitry, and sense, condition, or operate the connected device. The FTA communicates with an associated IOP, which in turn communicates with the HPMM(s) through the I/O Link Interface.

FTAs types

Standard types of FTAs, as described in Table 2-2, interface the field wiring and provide communication with an associated IOP. They are categorized as "standard" because Galvanically Isolated FTAs are also available as described in Table 2-3.

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Section 6 – Corrosion Protection Planning

6.1 Overview

Section contents

The topics covered in this section are:

Introduction

Corrosion is one of the leading causes of electronic printed circuit assembly board failure in harsh environments. Conformal coating of the assembly's printed circuits and components provides a solution for the problem. Conformally coated assemblies are completely covered with a thin layer of a special plastic material that is resistant to the corrosive effects of humidity and most chemical gases.

ATTENTION

Table 6-1 recommends the minimum equipment requirement that is based on environmental classification tests at the site where the equipment is installed.

Table 6-1 Environment Minimum Equipment Requirement

Environment Classification	Minimum Equipment Requirement
Mild (G1)	Non-conformally coated
Moderate (G2)	Conformally coated
Harsh (G3)	Conformally coated
Severe (Gx)	Conformally coated and installed in an environmentally hardened enclosure

G3 rating

All coated assemblies will withstand the effects of a G3 (harsh) rated environment. Uncoated boards are rated for mild (G1) environments. A harsh environment is defined by ANSI/ISA-S71.04-1985, "Environmental Conditions for Process Measurement and Control Systems: Airborne Contaminates."

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Environmental harshness levels

Table 6-2 defines environmental harshness levels for airborne contaminates.

Table 6-2 Harsh Environment Definitions from ANSI/ISA-S71.04-1985

Severity Level		G1 (Mild)	G2 (Moderate)	G3 (Harsh)	Gx (Severe)
Copper Reactivity Level (Angstroms/Month)		<300	<1000	<2000	≥2000
Contaminant Gas			Concentration (Parts/Billion)		
Group A	H_2S	<3	<10	<50	≥50
	SO_2, SO_3	<10	<100	<300	≥300
	Cl_2	<1	<2	<10	≥10
	NO_X	<50	<125	<1250	≥1250
Group B	HF	<1	<2	<10	≥10
	NH_3	<500	<10,000	<25,000	≥25,000
	O_3	<2	<25	<100	≥100

Gas concentrations

Gas concentrations are for reference purposes only and are believed to approximate the reactivity levels, assuming relative humidity is less than 50%. For each 10% increase in relative humidity above 50%, or change in relative humidity by greater than 6%/hour, the severity level can be expected to increase by one level.

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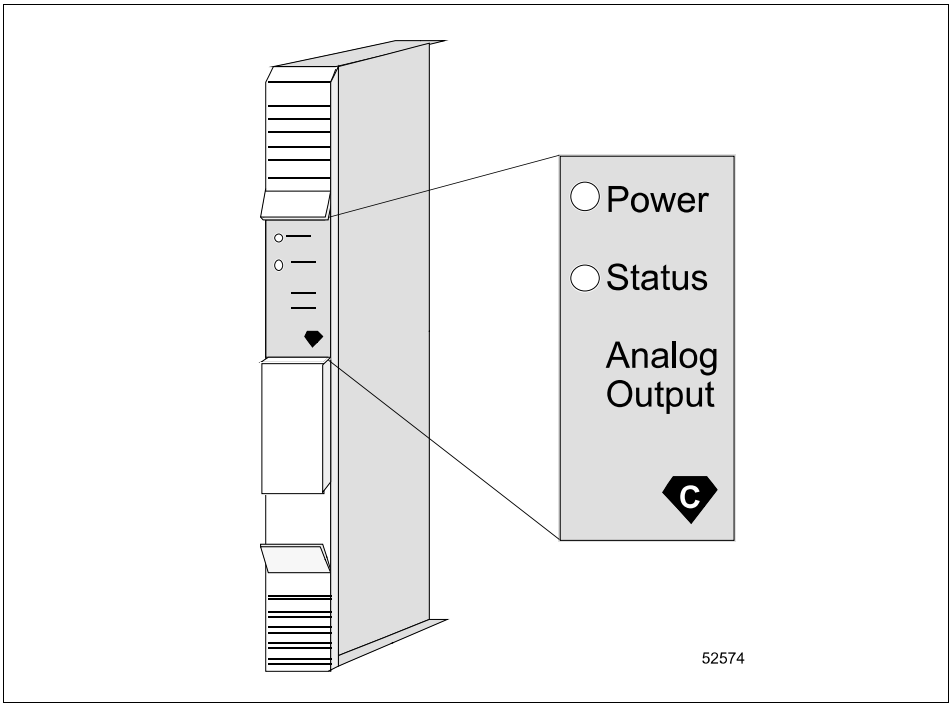
Conformal coating symbol

Conformally coated assemblies can be easily identified by a distinctive symbol located on the assembly. The symbol consists of a "C" that is surrounded by a solid diamond. The diamond universally symbolizes hardness. The symbol is intended to represent the hardened protection against harsh environments that conformal coating provides. Figure 6-1 illustrates the symbol on the faceplate of an Analog Output IOP.

Figure 6-1 Conformal Coating Symbol



Harsh Environment Enclosure

For those users who want to locate their IOPs closer to the process and outside the control room in a severe environment, another level of protection is required. Honeywell offers the availability of a harsh environment IOP enclosure that is capable of withstanding a Gx rated atmosphere. The product includes a sealed NEMA 4x stainless steel enclosure, a special 7-Slot card file with fans for air circulation to house conformally coated IOP and I/O Link Extender cards, and a 24 Vdc Power System that uses components found in the HPM AC Only Power System. There is no active external cooling required for external ambient temperatures of up to 60°C. The IOPs interface with the HPMM(s) in the control room by fiber optic I/O Link Extender. Standard IOP to FTA cables that are enclosed in sealed conduit provide the IOP to associated FTA interface. The FTAs are mounted in sealed NEMA 4x stainless steel enclosures that are provided by the user.

6.2 Model Numbers

Model numbers

Model numbers for conformally coated assemblies and upgrade kits are identified by a “MC” prefix, instead of the normal “MU” prefix for a noncoated assembly. An example would be a conformally coated Low Level Analog Input IOP. Its model number is MC-PAIL02. The model number of the noncoated version of the IOP is MU-PAIL02.

ATTENTION

ATTENTION—The High Level Analog Input and Analog Output IOPs are available only as conformally coated assemblies. There are no noncoated versions available. The model numbers are MC-PAIH03 and MC-PAOX03, respectively.

Assembly numbers

Typically, the part number’s tab for a conformally coated assembly has the format “x5x” (non-CE Compliant) or “x7x” (CE Compliant), where “x” can be any number, 1 through 9. This provides a standard method of identifying conformally coated assemblies.

Continued on next page

Conformally coated model list

Table 6-3 is a list of conformally coated High-Performance Process Manager assemblies.

Table 6-3 Conformally Coated Assembly Model Numbers

Model Number	Non CE Compliant Part Number	CE Compliant Part Number	Description
IOPs			
MC-PAIH03	N/A	51304754-150	High Level Analog Input (HLAI)
MC-PAIL02	N/A	51304481-150	Low level Analog Input (LLAI)
MC-PAOX03	51304672-150	51309152-175	Analog Output (AO)
MC-PAOY22	N/A	80363969-150	Analog Output (AO)
MC-PDIS12	N/A	51402625-175	Digital Input Sequence of Events (DI)
MC-PDIX02	N/A	51304485-150	Digital Input (DI)
MC-PDIY22	N/A	80363972-150	Digital Input (DI)
MC-PDOX02	N/A	51304487-150	Digital Output (DO)
MC-PDOY22	N/A	80363975-150	Digital Output (DO)
MC-PLAM02	N/A	51304362-150	Low Level Multiplexer (LLMux)
MC-PRHM01	N/A	51404109-175	Remote Hardened Low Level Multiplexer (RHMUX)
MC-PPIX02	N/A	51304386-150	Pulse Input (PI)
MC-PSDX02	N/A	51304362-250	Serial Device Interface (SDI)
MC-PSIM11	N/A	51304362-350	Serial Interface (SI)
MC-PSTX02	51304516-150	N/A	Smart Transmitter Interface (STI)
MC-PSTX03	N/A	51304516-250	Smart Transmitter Interface Multivariable (STIM)
Standard FTAs			
MC-TAIH02	51304453-150	N/A	High Level Analog Input/STI with compression term
MC-TAIH03	N/A	51309136-175	High Level Analog Input with compression terminals
MC-TAIH12	51304337-150	N/A	High Level Analog Input/STI with compression term
MC-TAIH13	N/A	51309138-175	High Level Analog Input with compression terminals
MC-TAIH22	80366195-150	N/A	High Level Analog Input/STI with compression term
MC-TAIH23	N/A	80366195-175	High Level Analog Input with compression terminals
MC-TAIH52	51304337-250	N/A	High Level Analog Input/STI with screw terminals

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Section 7 – CE Compliance

7.1 Overview

Section contents

The topics covered in this section are:

Introduction

To meet CE Compliance directives, card files, High-Performance Process Manager Module (HPMM) cards, Field Termination Assemblies (FTAs), Power Systems, and cables, namely IOP to FTA cables, power cables, and I/O Link Interface cables, are available and identified either by model number or by the assembly part number.

Hardware differences

Where applicable, this section describes general differences between the CE Compliant hardware and non-CE Compliant hardware.

Also discussed are the hardware combinations and rules that must be considered for CE Compliance.

CE Compliant hardware identification

Finally, where applicable, each subsection that is devoted to a particular type of hardware identifies the CE Compliant and the non-CE Compliant hardware.

Master Reference Ground

The use of a Master Reference Ground (MRG), which is separate from Safety Ground, is not acceptable for a CE Compliant installation. References to Master Reference Ground must be ignored and a single Safety Ground must be substituted.

CE Compliant installation

Only recommended CE Compliant hardware, cabling, and practices must be considered for a CE Compliant installation. Install only a single ground system.

7.2 Card Files

Introduction

All three card file types are available for CE Compliant applications. The CE Compliant models have three unique features. They are

- Filtered backpanel IOP connectors
- IOP connector ground panel(s)
- Rear backpanel shield

Unlike the non-CE Compliant 7-Slot and 15-Slot card files that are not dedicated HPMM or IOP card files, the CE-Compliant 7-Slot and 15-Slot card files are mechanically either HPMM or IOP card files. 7-Slot or 15-Slot IOP card files will not accept an HPMM card set.

Backpanel ground plane

The backpanel ground panel provides a ground plane for the body of the IOP connectors. The body of the connector in turn provides ground for the IOP to FTA cable shield when mated with the IOP connector.

Rear backpanel shield panel

Like the UCN connector shield enclosure, the backpanel shield panel provides EMI protection at the back of the backpanel.

IOP to FTA cables

Both the model MU-KFTAxx and MU-KFTSxx IOP to FTA cables can be used with both the CE Compliant and non-CE Compliant card files. However, only the CE Compliant card file models and the model MU-KFTSxx IOP to FTA cables together are acceptable as CE Compliant.

Model list

Table 7-1 lists the model numbers of the CE Compliant card files. All models are available without conformal coating (MU) and with conformal coating (MC). The PM/APM technology IOP Only card file is also included because it may exist when a PM or APM is upgraded to an HPM.

Table 7-1 Card Files

Card File Description	Non-Conformally Coated Model Number	Conformally Coated Model Number
Left 7-Slot HPMM	MU-HPFH03	MC-HPFH03
Right 7-Slot HPMM	MU-HPFH13	MC-HPFH13
15-Slot HPMM	MU-HPFX03	MC-HPFX03
Left 7-Slot IOP	MU-HPFI03	MC-HPFI03
Right 7-Slot IOP	MU-HPFI13	MC-HPFI13
15-Slot IOP	MU-HPFI23	MC-HPFI23
IOP Only (PM/APM)	MU-IOFX03	MC-IOFX03

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7.2 Card Files, Continued

Conversion kit	A model MU-ZPFI03 upgrade kit will convert a 7-Slot or 15-Slot HPMM card file to an IOP card file.

7.3 HPMM Cards

Introduction	The High-Performance Process Manager Module (HPMM) card set is CE Compliant.
Conformal coating	The HPMM card set is available with and without conformal coating.

7.4 IOPs

Introduction	Only the model MU-PAOX03 Analog Output IOP is available in a CE Compliant and non-CE Compliant version. All other IOP models are CE Compliant only.
Conformal coating	All IOP cards are available with and without conformal coating.

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Nonconformally coated IOPs

Table 7-2 lists the model numbers of the CE Compliant and non-CE Compliant IOP cards that are not conformally coated. Model numbers and part numbers identify the assemblies.

Table 7-2 IOPs—Nonconformally Coated

IOP Type	Model Number	Non-CE Compliant Part Number	CE Compliant Part Number
LLAI	MU-PAIL02	N/A	51304481-100
LLMux	MU-PLAM02	N/A	51304362-100
RHMUX	MU-PRHM01	N/A	51404109-125
HLAI	MU-PAIH03	N/A	51304754-100
STIM	MU-PSTX03	N/A	51304516-200
AO	MU-PAOX03	51304672-100	51309152-125
AO	MU-PAOY22	N/A	80363969-100
DI	MU-PDIX02	N/A	51304485-100
DI	MU-PDIY22	N/A	80363972-100
DISOE	MU-PDIS12	51402625-125	N/A
DO	MU-PDOX02	N/A	51304487-100
DO	MU-PDOY22	N/A	80363975-100
PI	MU-PPIX02	N/A	51304386-100
SDI	MU-PSDX02	N/A	51304362-200
SI	MU-PSIM11	N/A	51304362-300

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Conformally coated IOPs

Table 7-3 lists the model numbers of the CE Compliant and non-CE Compliant IOP cards that are conformally coated. Model numbers and part numbers identify the assemblies.

Table 7-3 IOPs—Conformally Coated

IOP Type	Model Number	Non-CE Compliant Part Number	CE Compliant Part Number
LLAI	MC-PAIL02	N/A	51304481-150
LLMux	MC-PLAM02	N/A	51304362-150
RHMUX	MC-PRHM01	N/A	51404109-175
HLAI	MC-PAIH03	N/A	51304754-150
STI	MC-PSTX02	N/A	51304516-150
STIM	MC-PSTX03	N/A	51304516-250
AO	MC-PAOX03	51304672-150	51309152-175
AO	MC-PAOY22	N/A	80363969-150
DI	MC-PDIX02	N/A	51304485-150
DI	MC-PDIY22	N/A	80363972-150
DISOE	MC-PDIS12	N/A	51402625-175
DO	MC-PDOX02	N/A	51304487-150
DO	MC-PDOY22	N/A	80363975-150
PI	MC-PPIX02	N/A	51304386-150
SDI	MC-PSDX02	N/A	51304362-250
SI	MC-PSIM11	N/A	51304362-350